

# UP-CHCR1

(UPC-CHT01)

Scenario Design Power(SDP): 9W

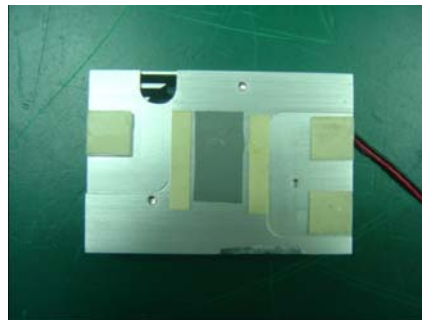
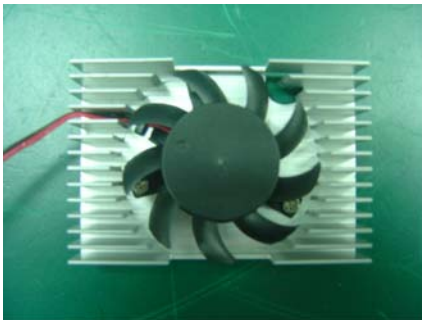
## Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>1. There is one temperature point marginal passed, the functions are stable,</u>			
<b>Test Result Summary</b>				
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	1
Defect Unsolved	0	0	0	1

Issue date	QE Manager	Test Engineer
2018 / 04/ 12	KJ Wang	Juno Cheng

## Sample Configuration & Quantity Under Test

- **Model name : UP-CHCR1 A0.2**
- **CPU : Intel® ATOM(TM) X5-Z8350 Processor 1.44 GHz**
- **Chipset: Intel® Cherry Trail**
- **Memory : DDR3L 4GB(Samsung-K4B8G1646D-MYK0)**
- **Storage : EMMC 64GB(Hynix - H26M78208CMR)**
- **BIOS : UCR1BM13(01/18/2018)**
- **Test Software : Windows 10 / Run PassMark Burn In Test 8.1 Pro (1025)**
- **Adapter: GS60A05 5V/6A, 30W MAX.**
- **CPU Cooler:**



# Thermal Image Analysis

**1. Test Date: 2018-04-10**

**2. Test Product: UP-CHCR1**

**3. Test Site: AAEON QE Dept.**

**4. Temperature Measurement:**

**4.1. 10 Channel Thermal Recorder:**

**4.1.1 OMRON**

**4.1.2 Model: ZR-RX25**

**Date of Calibration: 2017/11/24**

**Serial Number: TH-149**

**4.2. IR Scanner: Infrared Camera**

**4.2.1 NEC Avio Infrared Technologies Co., Ltd.**

**4.2.2 Model: Thermo GEAR G100W2-D**

**Date of Calibration: 2017/11/23**

**Serial Number: 1051444**

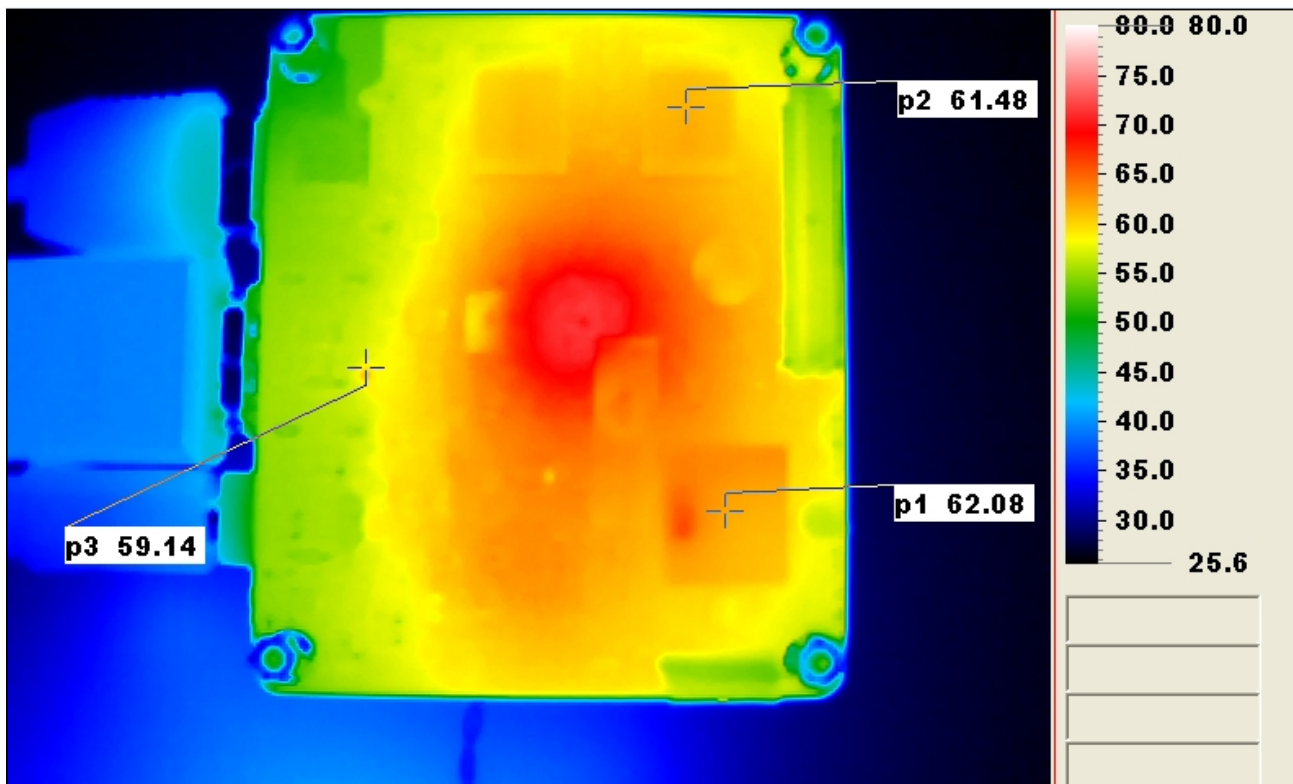
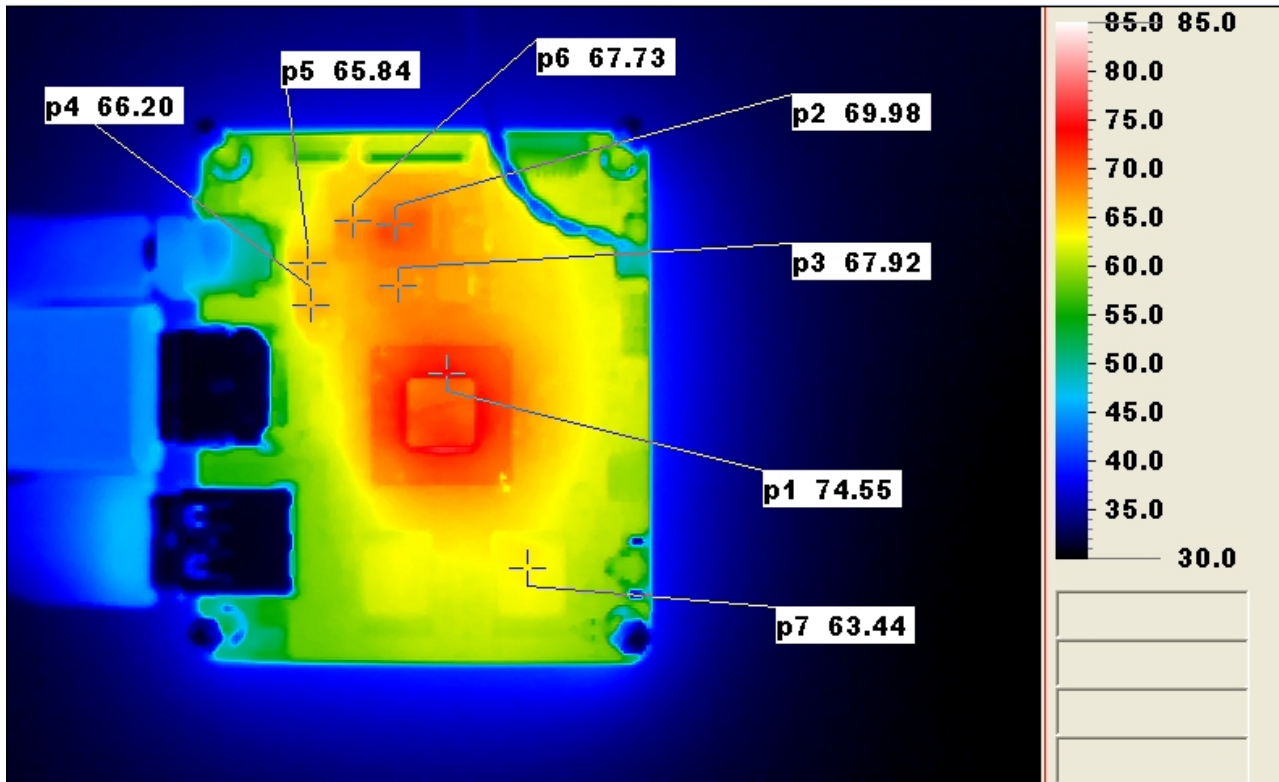
**5. Test Condition:**

**Test by DA-100: 26.0°C with Heat Sink + Fan**

**6. Take Picture Time:**

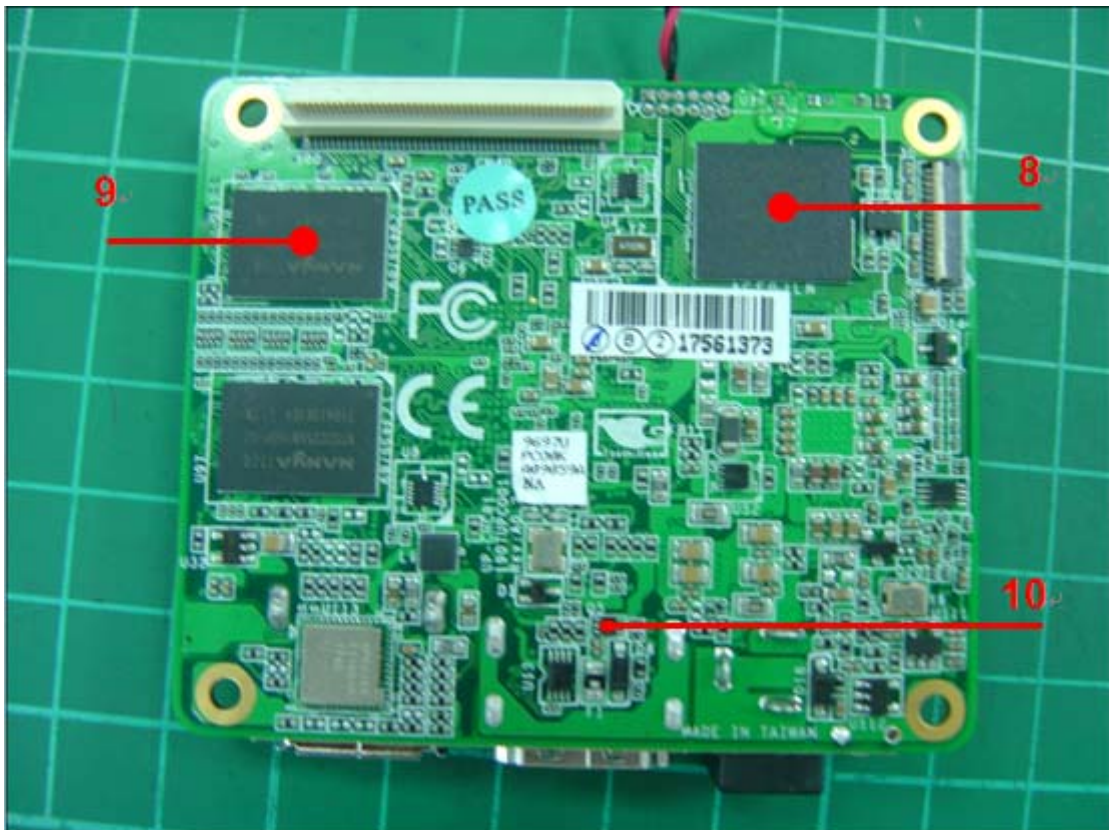
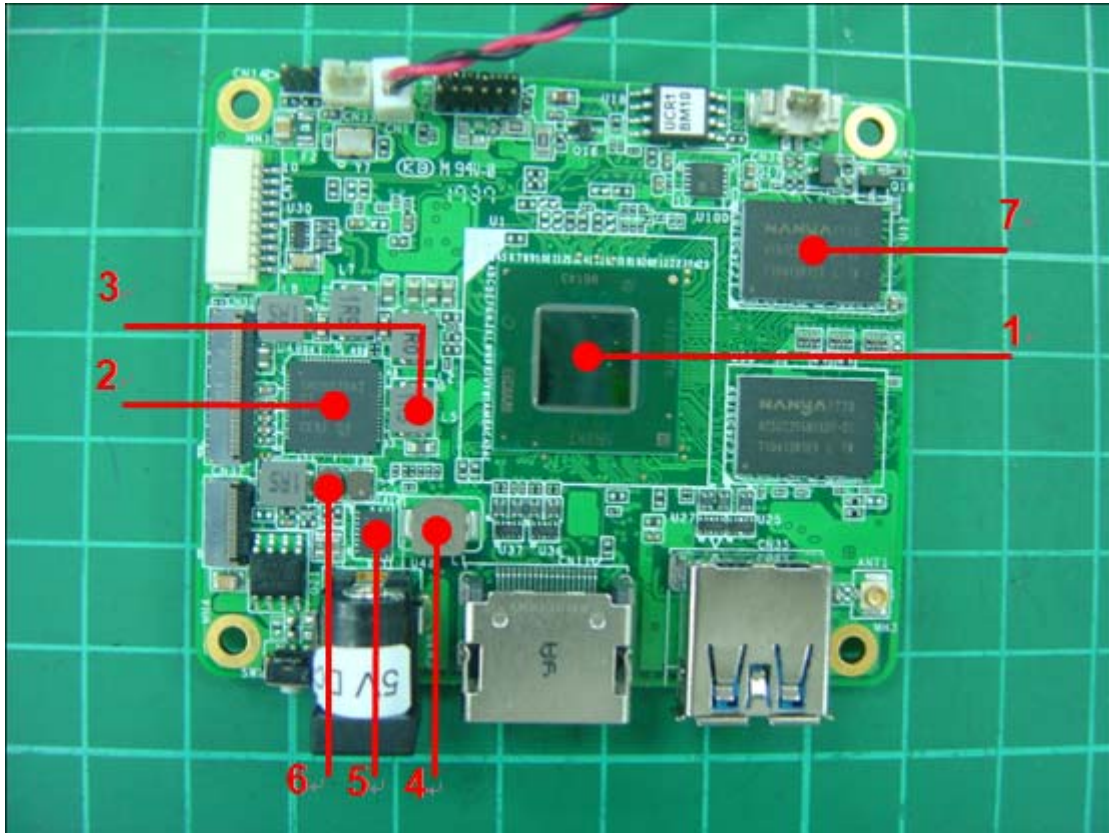
**After power on 2 hours**

### Temperature Profile Test: Component Side:



### Terminal Recorder:

Measuring Thermal Couple Position :



Using OMRON / ZR-RX45 test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2)		TPT(*3)	Note
				25.0°C	60°C		
1	U1	(TF)INTEL CPU.SOC.Cherry Trail-T3.x5-Z8350.1.92GHz.	90	56.0	91.0	Note3	
2	U49	(TF)IC.PMIC for Intel Cherry Trail. TI.SND9039A2CTRSKR	110	49.5	84.5		
3	L5	(TF)COIL. SMD.GOTREND.GSTD4020PM-1R0M	125	46.8	81.8		
4	L1	(TF)COIL.NEC/TOKIN.MPLCG0530L1R5	125	41.1	76.1		
5	U48	(TF)IC.Synchronous tep down.SMD.MPS.MP8762GLE-Z	110	43.8	78.2		
6	L3	(TF)COIL. ZenithTek.ZADP-252012MES-R47M	125	43.9	78.9		
7	U12	(TF)IC.4G.DDR3L-1600.SDRAM.I.SMD.NT5CC256M16DP-DI	95	39.4	74.4		
8	U11	(TF)IC.eMMC Flash.SMD.Kingston.EMMC32G-M525-A51	115	55.4	90.4		
9	U19	(TF)IC.4G.DDR3L-1600.SDRAM.SMD.NT5CC256M16DP-DI	95	49.2	84.2		
10	Q5	(TF)PWR.Dual N-Channel MOSFET SMD.ROHM.EM6K1GT2R	150	52.4	87.4		

Note(\*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "TAT" indicates the actual measured temperature under product specification.
3. "TPT" indicates the predicted temperature under 25°C working environmental.
4. Judgment Criteria:
  - Fail :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
  - Margin :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
  - Pass :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.
5. RTC battery avoid to put on heat position. Please do not exceed battery temperature specification.
4. Defect NO.: [D161209LAE01](#)